

# **PRINTED CIRCUIT BOARD (PCB) ASSEMBLY CAPABILITIES**

## **Printed Circuit Board Assembly General Capabilities**

Just-In-Time Prototypes

Quick Turnaround Prototype

## **Circuit Board Construction**

Combined Construction (Rigid and Flex)

Copper Clad

Double-Sided

Etched

Exotic

Flexible

Metal Core Insulated

Mixed Technology (SMT and Thru Hole)

Molded 3D

Multilayer

Plated-Through-Hole (PTH)

Silver Through Hole

Single-Sided

Solder Mask Over Bare Copper

(SMOBC)

Surface Mount

## **Materials**

Fiberglass

FR-4

Getek

Kevlar

Mylar

Phenolic

Polyester

Polyimide

## **Number of Board Layers**

2 to 14 Layers

## **Circuit Board Features**

Fine Line

Flush Surface

Lead Free

PCI

Plug-In

Surface Mount

Thru Hole

Rigid-Flex

Single Sided

Double Sided

Micro BGA

Circuit Board to Box

Conformal Coating

Fine Pitch

## **Assembly Methods**

Automated Assembly

Hand Insertion

Hand Soldering

Point-to-Point Wiring

Reflow

Wave Solder

Wire Wrapping

## **Circuit Board Features**

Board Fabrication	Layout
Burn-In	Plating
Component Programming	Potting
Component Sourcing	Repair
Conformal Coating	Rework
Contract Manufacturing	Routing
Cutting	Stamping
Design	Testing
Inspection	Wiring

## **Turnaround Time**

Component Dependent

## **Production Volume**

Contract Dependent

## **ADDITIONAL INFORMATION**

### **Industry Focus**

O.E.M Industrial	Industrial Automation
Instrumentation	Medical
Electronics	Telecommunications

### **Industry Standards**

#### IPC

Originally Institute for Interconnecting and Packaging Integrated Circuits, now called IPC. These are standards for printed circuit board design and manufacturing.

#### ISO

International Organization for Standardization

